TRIAC For High Power

TG40E80

 $I_{T(RMS)} = 40A$, $V_{DRM} = 800V$

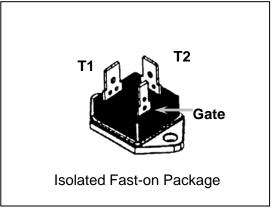
SanRex Triac **TG40E80** is specially designed use for high power AC switching application. Thanks to SanRex's new isolated diffusion technology, the Triac **TG40E80** features high dv/dt, dv/dt/c and very low on-state voltage. These benefits make this design an extremely reliable and efficient device for use in wide variety of applications.

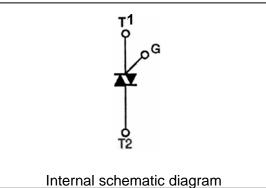
Features

- * High Power
- * High Surge Current
- * Low On-State Voltage
- * High Commutation Performance
- * UL registered E76102

Typical Applications

- * Home Appliances
- * Water Heaters
- * Heater Controls
- * Lighting Controls
- * Temperature Controls





< Maximum Ratings> (Ti = 25°C unless otherwise noted)

< waximun	n Ratings>	(1) = 25 C unless other	erwise notea)	
Symbol	Item	Conditions	Ratings	Unit
V_{DRM}	Repetitive Peak Off-state Voltage		800	V
I _{T(RMS)}	R.M.S. On-state Current	T _C = 64°C	40	Α
I _{TSM}	Surge On-state Current	One cycle, 60Hz, Peak, non-repetitive	420	А
l ² t	I ² t (for fusing)	Value for one cycle surge current	730	A ² s
P _{GM}	Peak Gate Power Dissipation		10	W
P _{G(AV)}	Average Gate Power Dissipation		1	W
I _{GM}	Peak Gate Current		3	А
V _{G M}	Peak Gate Voltage		10	V
di/dt	Critical Rate of Rise of On-State Current	I_G =100mA, V_D =1/2 V_{DRM} , di_G /dt=1A/ μ s	50	A/Fs
Tj	Operation Junction Temperature		-40 to +125	°C
Tstg	Storage Temperature		-40 to +150	°C
V _{ISO}	Isolation Breakdown Voltage	R.M.S., A.C. 1 minute	2500	V
	Mounting Torque (M4)	Recommended value 1.0 – 1.4 N*m	1.5	N*m
	Mass	Typical Value	23	g

SanRex_®

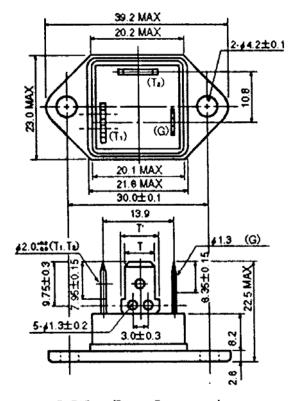
TRIAC for High Power

TG40E80

< Electrical Characteristics >

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Symbol	Item	Conditions	Ratings		Unit	
			Min.	Тур.	Max.	Offic
I _{DRM}	Repetitive Peak Off-state Current	$T_j = 125$ °C, $V_D = V_{DRM}$			5	mA
V_{TM}	Peak On-State Voltage	I _T =60A, Instant measurement			1.4	V
I _{GT} 1 ⁺	QI	$V_D = 6V$, $I_T = 1A$			50	mA
I _{GT} 1	QII Gate Trigger Current				50	mA
I _{GT} 3 ⁺	QIV Gate Higger Current				-	mA
I _{GT} 3⁻	QIII				50	mA
$V_{GT}1^+$	QI	$V_D = 6V$, $I_T = 1A$			1.5	V
$V_{GT}1^{-}$	QII Gate Trigger Voltage				1.5	V
$V_{GT}3^{+}$	QIV Gate Higger Voltage				-	V
V _{G T} 3⁻	QIII				1.5	V
V_{GD}	Non-Trigger Gate Voltage	$Tj = 125^{\circ}C, V_D = 1/2V_{DRM}$	0.2			V
dv/dt	Critical Rate of Rise of Off-State Voltage	Tj = 125°C, V _D =1/2V _{DRM} , Exponential wave	500			V/Fs
(dv/dt)c	Critical Rate of Rise of Commutation Voltage	Tj =125°C, V _D =2/3V _{DRM} , (di/dt)c= 10 A/ms	6			V/Fs
I _H	Holding Current			30		mA
Rth(j-c)	Thermal Resistance	Junction to case			1.3	°C/W



T₁:TAB250 (T=6.35, T=8.25, t=0.8) T₂:TAB250 (T=6.35, T=8.25, t=0.8) G:TAB187 (T=4.75, T'=5.7, t=0.8)

^{*} Dimensions in millimeters